

2012



Looking to Simplify Your 3G and 4G Smartphone Design?

Choose the Highly Integrated TRITIUM Duo™ Family



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Connecting the Digital World
to the Global Network®

TriQuint 
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Revolutionary Size, Performance and Flexibility

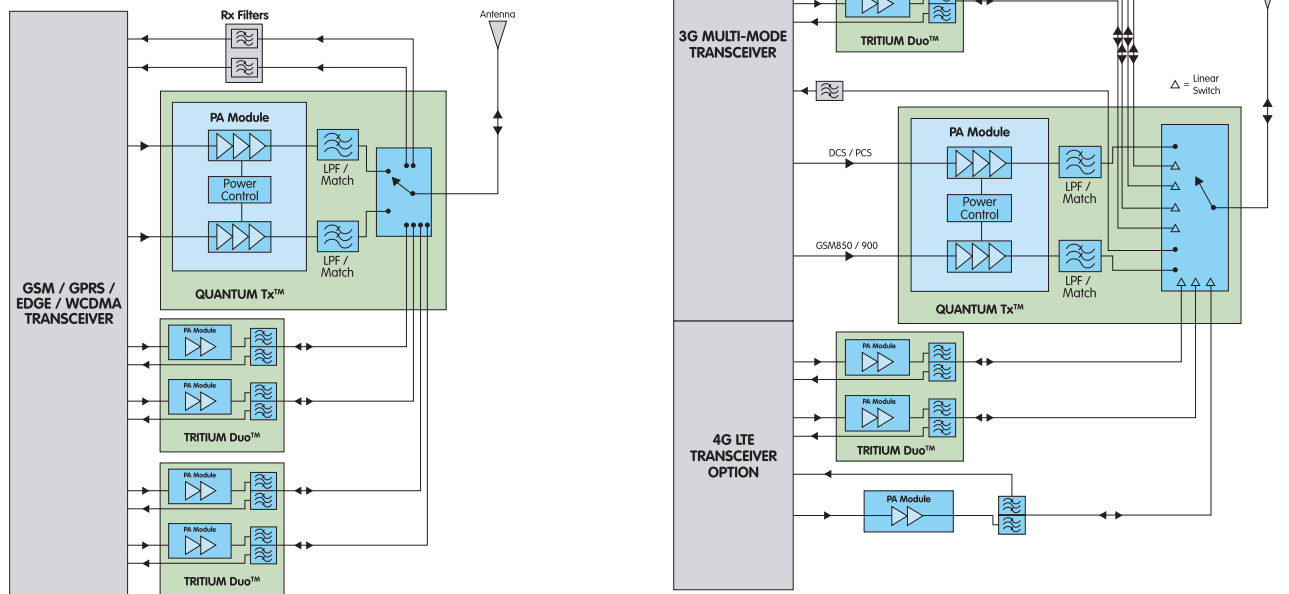
With the exploding demand for global 3G and 4G mobile devices, TriQuint continues to advance the development of highly integrated RF front-end solutions that deliver efficient and innovative wireless design possibilities.

TriQuint's TRITIUM Duo™ family of PA-Duplexer modules offers an integrated approach for compact designs – making it possible to replace up to 12 discrete components with a single package and allowing you to use a similar footprint across multiple mobile platforms. By supporting popular global band combinations, the integrated solution provides greater flexibility than ever before.

High performance is achieved since no switching is required after amplification. Our cutting-edge passives allow for multi-mode operation across 3G and 4G standards. A quad-band solution using two TRITIUM Duos is just over 50mm², half the footprint of a comparable discrete solution.

TriQuint's proprietary CuFlip™ technology and Wafer Level Packaging (WLP) of SAW filters help create these dramatic size reductions.

The TRITIUM Duo is one more proven way TriQuint engineers are delivering innovative solutions for the most complex mobile design challenges.



TRITIUM Duo™ Family - CDMA / WCDMA / HSUPA / LTE

Part #	Description	Size (mm)	Bands	Features
TQM6M6218	Integrated 2-in-1 PA-Duplexer Module	6.0x4.5x1.0	Bands 1 & 8	DC / DC, 1-Bit (Hi / Med Power Modes)
TQM6M6225	Integrated 2-in-1 PA-Duplexer Module	6.0x4.5x1.0	Bands 2 & 5	DC / DC, 1-Bit (Hi / Med Power Modes)
TQM6M6214	Integrated 2-in-1 PA-Duplexer Module	6.0x4.5x1.0	Bands 1 & 4	DC / DC, 1-Bit (Hi / Med Power Modes)

